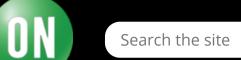
ON Semiconductor®







Manufacturing Info
MBOI
Specifications

## PH4 ISPL (ATEC) (CU) MBOI Data

Supply
Purchasing/Payables
Planning
APSFR

Search Files:		Search	MBOI Masters
ASY (745) TS	ST (707)		

Factory Information

<u>Capacity Statement</u>
<u>Quality</u>
<u>Global EBR2</u>
<u>Global EBR3 Revamp</u>
<u>Global EBR5</u>
<u>External Manufacturing</u>
<u>MPE</u>

Data Exchange

<u>Document Exchange</u>

<u>Intransit</u>

<u>Exceptions</u>

	Manufacturing Bill of Information (MBOI)					
Part Number	99MC74HCU04ADTG	Part Type	Assembly Part			
Site   Name   Loc Cod	PH4   ISPL (ATEC)   CU	File Name	PH4_MC74HCU04ADTR2G_99MC74HCU04ADTG_ASY			
Flags	Non Safe Launch Item No Global Hold Flag	Part Qual Target Market:	U   Unspecified			
Part Version	1	Part Version Date- Time	2019-OCT-30 18:13:00 (GMT +7)			

	Orderable Part Section - OPN						
Part Number   Desc	MC74HCU04ADTR2G   LOG CMOS INVERTER HEX	Market PN					
Lifecycle Phase	Production	Part Class   Desc	AA   ASSEMBLED AND TESTED				
Marketing Product Lifecycle	Follow Part Lifecycle	Part Sub Type	OPN				
Part Release Status   Desc	MC-M   Mass Production	Part Usage	STD				
Case Outline	948G-01 <b>P</b>	PAL4 Code   Desc	I				
Product Data Sheet	MC74HCU04A-D.PDF						
ERP Resource Code - ASY   Desc	7048   TSSOP 14 5*4.4 CPR PBF H	OPN Part Qual Target Market	U   Unspecified				
Packing Configuration	TSSOP-14_948G_REEL_2500_FBQ5000	Eng Package Type	TSSOP-14				

Assembly_Part_Section - ASY					
Part Number	99MC74HCU04ADTG	Description	LOG CMOS INVERTER HEX		
Lifecycle Phase	Production	Part Usage	STD		
Part Release Status   Desc	MC-M   Mass Production	Part Sub Type	ASY		
PAL4 Code   Desc		ERP Resource Code - ASY   Desc	7048   TSSOP 14 5*4.4 CPR PBF H		
Case Outine	948G-01 <b>P</b>	Package Type	TSSOP-14		
ECAT Override		Actual Lead Count	14		
Package Assembly Platform	SOSM - Small Outline Surface Mount	Assembly Baseline Spec			
Assembly Process Flow Spec		Assembly Spec(s) - Global			
Lot Processing Restrictions	Standard				
ITAR Part Flag	N	Customs Configuration	8542.39.0001		
Customs ECCN Code	EAR99	Customer Consigned Flag	N		
Compressed?		Compressed Part Number			
Wettable Process Type		Wettable Flank Flag			
Site Notes					

	BOM Components							
Alternate 002	Part Number	Part Sub Type	Line	Preference	Group	Qty	Description	Lifecycle Phase
Primary Die	DBTHCU04ABH44	WDQ	001	01	0	1	TOWER HSL DIE	Production
	Die Size (X + Y W/	Scribe Stree	t): 539	x 604			PDPW : 46911	
Package Kit	N96938G003	PKT	002	01	0	1	PKGKIT TSSOP14 CU (PH4)	Production
	Piece Parts							
	1360100039	FRAME	010	01	0	1	LF, TSSOP14LD 0.9398 x 0.9398mm	Production
	1010150057	EPXY	020	01	0	0.000159	DA Sumitomo CRM- 1076WB	Production
	1360162001	WIRE	030	01	0	0.02180	BW Maxsoft 0.8 mil Cu Wire	Production
	1360194003	MOLD	040	01	0	0.125	MC EMC Sumitomo G600 13 X 5.0	Production
BOI 67-Bonding Diagram	67AON45339E O	DOC	003	01	0	1	MC74HCU04ADT	Production

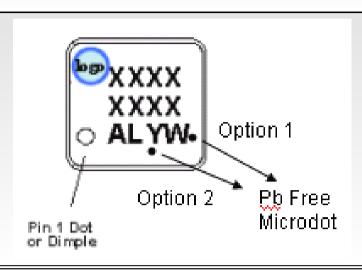
Marking Header Section				
Marking Style Configuration	TSSOP_2L_8C			
Standard Marking Flag		ON	· ·	
PB Free Mark Character Flag				

## Front Side Marking

Line1:HCU

Line2:04A

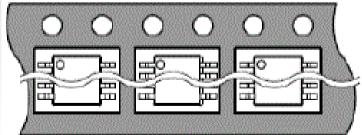
Tracecode:Y(LYW)



	Marking Details Section						
Trace Code Coding Std	ON_STD_021C : A(L)(YW) : (A01)(L11)(Y02L) (W02L)	Trace Code Coding Custom					
Trace Code Legend - Front	A: Assembly Site L: Wafer Lot Number YW: Assembly Start Week						
Trace Code Legend - Back							
Trace Code Spec	12MON00232D KS	Part Marking Source	PDM System				
Part Marking Image/CAD Document		Marking Style Image Document	18AON90319E O				
Custom Logo Document		ON Logo Document	18AON77167F O				
Final Test Specification	48AON21923D G						

OPN Packing Section						
PCQ Container   Desc	REEL   Tape and Reel	PCQ Quantity	2500			
MPQ Container   Desc	REEL   Tape and Reel	MPQ Quantity	2500			
Intermediate Full Box Container Type   Intermediate Box Container Size   Intermediate Full Box Container Quantity	       5000	Intermediate Full Bag Container Type   Intermediate Bag Container Size   Intermediate Full Bag Container Quantity				

Pin 1 Toward Upper Left



Labeling Section				
MSL	1	MSL Temperature	260	
Pb Free Leads Flag	Υ	Halide Free Flag	Υ	
Pb Free Die Attach Flag	Υ	Lead Finish Category (eCAT)	e4	

Document Group Section					
Document Num	Revision	Release Date	Title		
12MON00232D	KS	14-Nov-19	Standard Marking for Integrated Circuits		
48AON21923D	G	25-Apr-19	MC74HCT04A, MC74HCU04A, MC74HC04A Series		
67AON45339E	0	31-Aug-09	MC74HCU04ADT		

BOM Links					
Up/Down Direction Site Top Part Link					
Up	PH4	MC74HCU04ADTR2G	PH4_MC74HCU04ADTR2G_MC74HCU04ADTR2G_TST.XML		

	Revision History					
Rev	Rev Date	Details				
1	2019-OCT-23 23:01:46	Initial version				

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